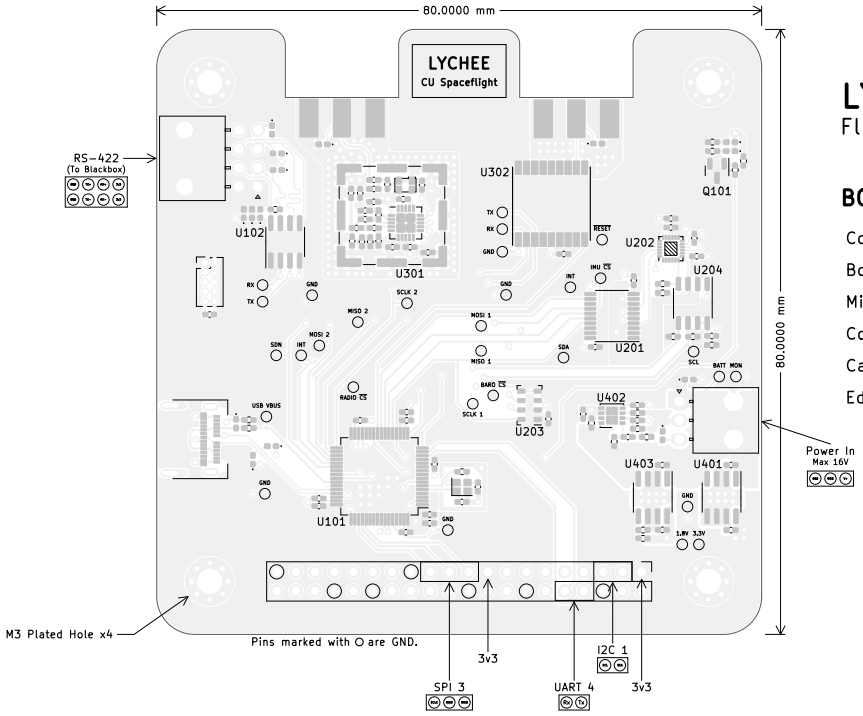

LYCHEE
Flight Computer

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6000 mm
Board overall dimensions:	80.0000 mm x 80.0000 mm		
Min track/spacing:	0.1500 mm / 0.1250 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.0138 mm	Blue	3.8	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	FR4	0.2104 mm		4.5	0.02
In1.Cu	copper		0.0152 mm		1	0
Dielectric 2	core	FR4	1.065 mm		4.5	0.02
In2.Cu	copper		0.0152 mm		1	0
Dielectric 3	prepreg	FR4	0.2104 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0 mm	Blue	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

Drawn By H. Franks
Cambridge University Spaceflight
Sheet: Assembly
File: flight-computer.kicad_pcb

Title: Lychee Flight Computer

Size: A4	Date: 2021-12-31	**Rev: 1**
KiCad E.D.A. kicad (6.0.6)		Id: 1/1